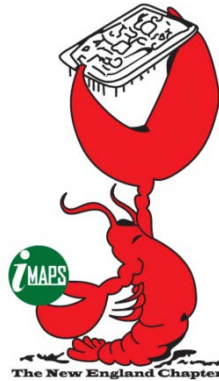


# Call for Papers

## iMAPS New England – 46<sup>th</sup> Symposium & Expo

The Largest New England Symposium Dedicated to  
Microelectronics and Packaging

3 Awards - \$500, \$300, \$200 for  
Best Student Papers / Posters



**May 7<sup>th</sup>, 2019**

Boxboro Regency, Boxborough, Massachusetts

The New England Chapter Symposium Technical Program Committee seeks papers that demonstrate how new technologies and applications are expanding and redefining microelectronics. Areas of interests include:

Industry	Advanced Processes & Materials
<ul style="list-style-type: none"><li>• Biomedical Electronics</li><li>• Telecom - Microwave</li><li>• Military Electronics</li><li>• Consumer Electronics</li><li>• Renewable Energy: Fuel Cells, Solar, Wind</li><li>• Thermal Management</li><li>• Manufacturing, Outsourcing &amp; Quality</li><li>• Solar/PV</li><li>• High Performance Interconnects and Boards</li><li>• Imaging Sensors</li><li>• Emerging Technologies</li></ul>	<ul style="list-style-type: none"><li>• 2.5 / 3D and High Density Packaging</li><li>• Photonic / Optoelectronic Packaging</li><li>• LED Packaging</li><li>• MEMS and Nano Packaging</li><li>• Underfill, Encapsulants, and Adhesives</li><li>• Green Packaging / Compliance with RoHS</li><li>• Flip-Chip and Bumping: Processes, Reliability</li><li>• Wirebonding and Stud Bumping</li><li>• Embedded and Integrated Passives</li><li>• Ceramic, Polymer and Conductive Materials</li><li>• Conformal Electronic Materials</li><li>• Wearable / Printed Electronics</li></ul>

Please send 250 word abstract to [Dmitry Marchenko – dmarchenko@gmail.com](mailto:dmarchenko@gmail.com)

Or Send to: [Abstracts@imapsne.org](mailto:Abstracts@imapsne.org)

Submission form and more details available at - [www.imapsne.org](http://www.imapsne.org)

**Deadline for Abstract Submission – December 31, 2018**